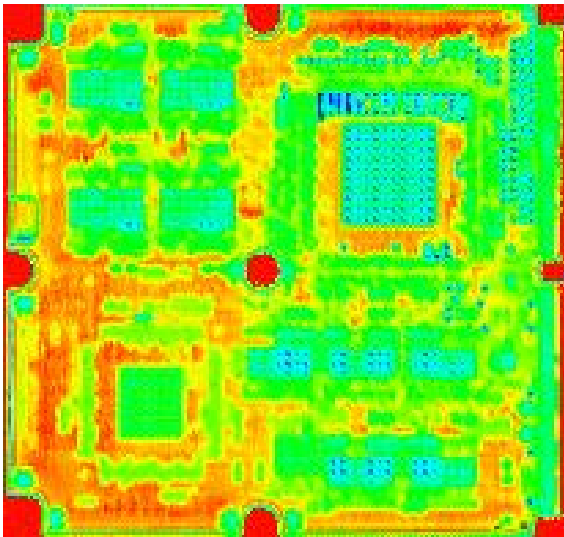


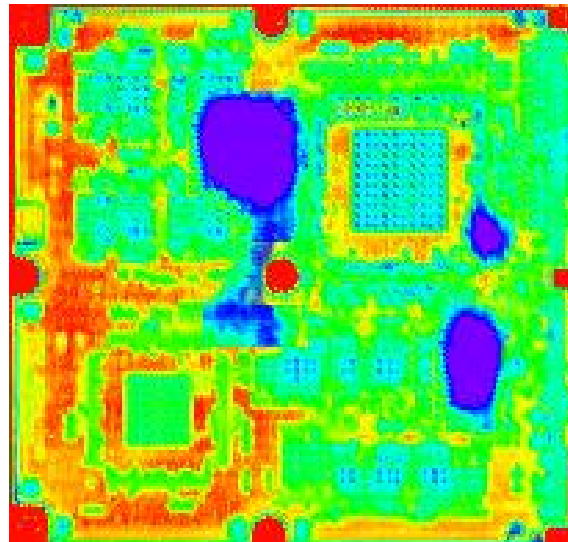
NONDESTRUCTIVE TESTING OF MULTI-LAYER PC BOARDS FOR DETECTION OF NONBONDS

Ultrasonic Thru-Transmission C-Scan “Hydroscan” is a test method capable of detecting delaminations and nonbonds without damaging the test part.

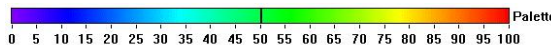
Delaminations and nonbonds in printed circuit boards are responsible for component overheating (due to the poor thermal conductivity of delaminated layers), as well as mechanical failure of vias due to interlaminar separation.



Good Circuit Board without non-bonds



Defective Circuit board showing non-bonds (Blue Areas)



QMI’s Ultrasonic Testing provides fast, efficient and a cost-effective means to achieve:



- Product Reliability
- Quality System Integrity
- Product Marketability



AC7114 Nondestructive Testing
AC7004 Inspection and Test Quality
System